

PMP7038RevB_BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
2	C11 C27	330n	Capacitor, Ceramic,	0805	Std	Std
2	C1-2	68u	Capacitor, Tantalum, 16V, [20%]	6032	16TQC68M	Sanyo
2	C12-13	1n	Capacitor Y2, Ceramic X7R, 2.5kV, 10%	1812	GA342DR7GF102KW02L	MuRata
2	C14 C17	100n	Capacitor, Ceramic, 16V, X7R	0603	Std	Std
2	C15, C28	100p	Capacitor, Ceramic, 50V, C0G, 20%	0603	Std	Std
1	C16	DNP	Capacitor, Ceramic, 16V, C0G, 20%	0603	Std	Std
3	C20-22	150u	Capacitor, Tantalum, 6.3V, [20%]	6032	6TPA150M	Sanyo
1	C23	100n	Capacitor, Ceramic, 6V3, X7R, 20%	0603	Std	Std
1	C29	10n	Capacitor, Ceramic, 16V, X7R	0603	Std	Std
1	C3	4u7	Capacitor, Ceramic, 6V3, X7R, 10%	0603	Std	Std
1	C30	220p	Capacitor, Ceramic, 50V, C0G, 10%	0603	Std	Std
1	C31	220p	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C32	10n	Capacitor, Ceramic, 16V, X7R, 10%	0603	Std	Std
1	C33	DNP	Capacitor, Ceramic, 16V, X7R, 10%	0603	Std	Std
4	C4-5 C18-19	22u	Capacitor, Ceramic, 10V, X5R, 20%	1210	Std	Std
1	C6	10u	Capacitor, Ceramic, 10V, X5R, 20%	1206	Std	Std
1	C7	470p	Capacitor, Ceramic, 16V, X7R	0603	Std	Std
6	C8-10 C24-26	330n	Capacitor, Ceramic, 25V, X7R	0805	Std	Std
1	D1	HRW0702A	Diode, Schottky, 700-mA, 20-V	SOT23	HRW0702A	Hitachi
2	D2-3	SS3P4L-E3	Diode, Schottky, 40V, 3A	TO-277A(SMPC)	SS3P4L-E3	Vishay
1	D4	Red	Diode, LED 0805	0805	Std	Std
1	D5	BAS40-04	Diode, Dual series Schottky, 40-V	SOT23	BAS40-04	On Semi
2	J1-2	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	OST
1	L1	220u	Inductor, SMT, 0.37A, 0.72ohm	0.260 x 0.260 inch	DR74-221	Cooper Bussman
1	L2	1.2u	Inductor, SMT, 5.4A, 0.04 ohm	0.260 x 0.260 inch	LPS6235-120ML	Coilcraft
1	L3	0.56u	Inductor, SMT, 5.4A, 0.04 ohm	0.260 x 0.260 inch	74477450056	WE
8	P1-8					STD
2	Q1-2	IRF7460P	MOSFET, N-Chan, 20V 12A, 10mOhm	{Size}	IRF7460P	IR
1	R1	1	Resistor, Chip 1/4 watt, ±1%	1206	Std	Std
1	R11	1.25k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R12	1k	Resistor, Chip 1/4 watt, ±1%	1206	Std	Std
1	R15	10	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R16	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R17	3.74k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R18 R22	DNP	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R19	270	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R2	180	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R20	33k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R21	1k24	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R23	0.22	Resistor, Chip 1/4 watt, ±1%	1206	Std	Std
1	R3	22.1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R4	2.2k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R5 R10	1	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R6 R9 R13	DNP	Resistor, Chip, 1/10W, 1%	0805	Std	Std
2	R7 R14	3k3	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R8	806	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	TP1-6, TP8-10	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	TP7	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	MC33063AD	IC, 1.5 A Boost/Buck/Inverting SW Reg.	SO8	MC33063AD	TI
1	U2	UCC25600D	IC, Resonant Mode Controller	SO-8	UCC25600D	TI
1	U3	CNY17-4TV-M	IC, Optocoupler, 70 Vceo, Viso 5000Vrms, Wide Lead Space	DIP6 [400mil wide]	CNY17-4TV-M	FAIRCHILD
1	U4	TLV431CDBZR	IC, Low-Voltage Adjustable Shunt Regulator	SOT23-3	TLV431CDBZx	TI

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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